

Features

- Glass passivated chip
- Super fast switching for high efficiency
- For surface mounted applications
- Low forward voltage drop and high current capability
- Low reverse leakage current
- Plastic material has UL flammability classification 94V-0
- AEC-Q101 qualified



DO-214AA (SMB)

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	AES3 AB	AES3 BB	AES3 CB	AES3 DB	AES3 FB	AES3 GB	AES3 JB	AES3 KB	AES3 MB	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	105	140	210	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	800	1000	V
Maximum Average Forward Rectified Current ($T_L=100^\circ\text{C}$)	$I_{F(AV)}$							3.0			A
Peak Forward Surge Current 8.3 ms Single Half Sine-wave Superimposed on Rated Load	I_{FSM}							100			A
Operating Junction Temperature Range	T_J						-55 to +150				$^\circ\text{C}$
Storage Temperature Range	T_{STG}						-55 to +150				$^\circ\text{C}$

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	AES3 AB	AES3 BB	AES3 CB	AES3 DB	AES3 FB	AES3 GB	AES3 JB	AES3 KB	AES3 MB	Unit
Maximum Instantaneous Forward Voltage @3.0A DC	V_F		0.92			1.25		1.7			V
Typical Junction Capacitance ²	C_J				45						pF
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R ($T_J=25^\circ\text{C}$)				10						uA
	I_R ($T_J=125^\circ\text{C}$)				500						uA
Typical Reverse Recovery Time ¹	t_{rr}				35						nS
Typical Thermal Resistance Junction to Ambient ⁴	$R_{\theta JA}$				50						$^\circ\text{C}/\text{W}$
Typical Thermal Resistance Junction to Lead ³	$R_{\theta JL}$				10						$^\circ\text{C}/\text{W}$

- Notes:**
1. Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$
 2. Measured at 1 MHz and Applied $V_R=4.0$ Volts
 3. Thermal Resistance junction to Lead.
 4. Thermal Resistance junction to Ambient.

Typical Characteristics Curves

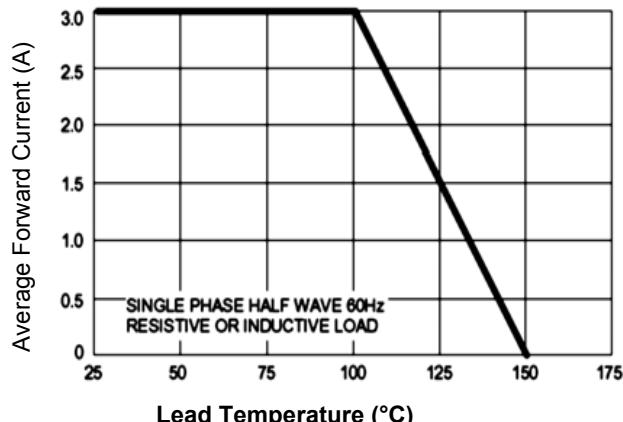


Figure 1. Forward Current Derating Curve

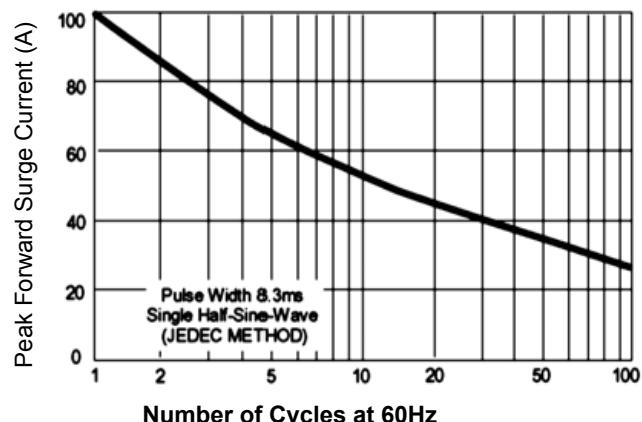


Figure 2. Maximum Non-Repetitive Surge Current

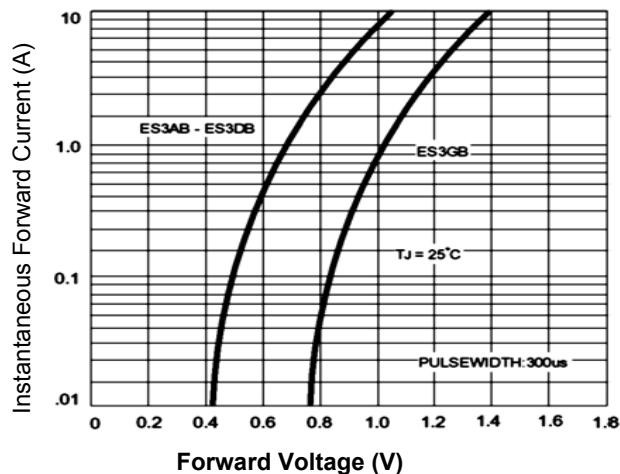


Figure 3. Typical Forward Characteristics

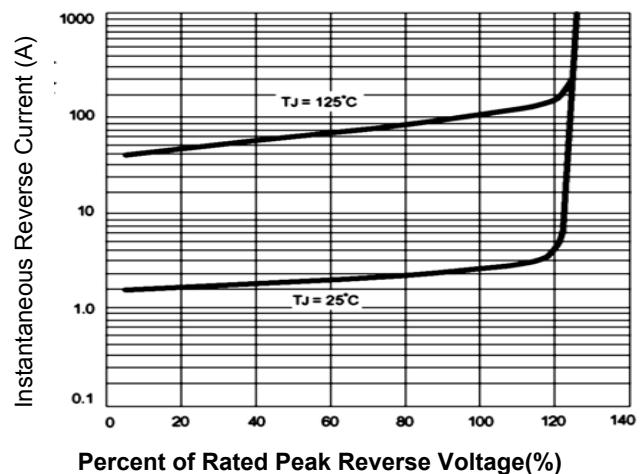
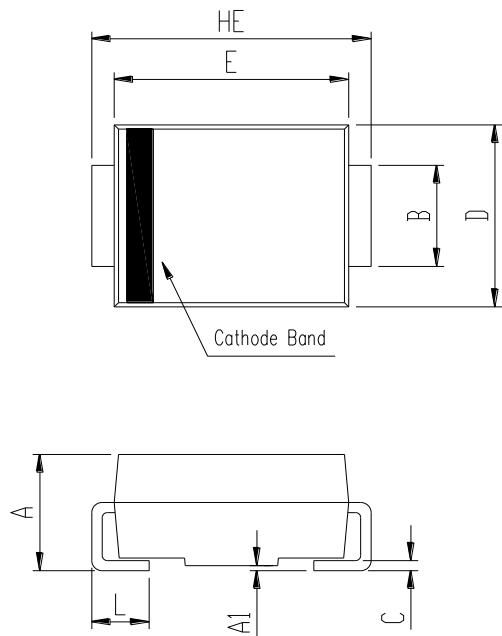


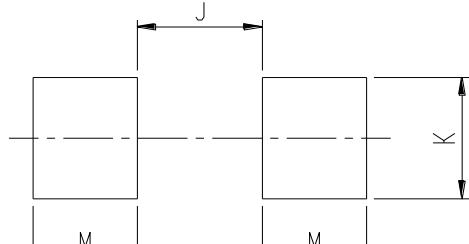
Figure 4. Typical Reverse Characteristics

Package Outline Dimensions DO-214AA (SMB)



SMB (DO-214AA)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.99	2.61	0.078	0.103
A1	0.00	0.20	0.000	0.008
B	1.93	2.08	0.076	0.082
C	0.15	0.31	0.006	0.012
D	3.48	3.73	0.137	0.147
E	4.25	4.75	0.167	0.187
HE	5.26	5.46	0.207	0.215
L	0.90	1.41	0.035	0.056

Recommended Pad Layout



SMB Recommended Pad Layout (Reference Only)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	-	2.60	-	0.102
K	2.20	-	0.087	-
M	1.80	-	0.071	-